

Xilinx T2 Telco Accelerator Card

OVERVIEW

Xilinx T2 Telco Accelerator card provides high performance, low latency, and power efficiency needed for 5G O-DU deployments. The turnkey solution enables operators, system integrators, and OEMs to get to market quickly and to simplify the deployment of services at the edge. It has a strong channel coding scheme of Low Density Parity Check (LDPC) code for reliable data transmission over 5G radio interface and it also supports turbo coding Forward Error Correction (FEC) mechanism for data transmission over 4G interface.

T2 card uses 16nm Zynq UltraScale+ RFSoC device to accelerate real-time baseband (L1) lookaside processing. It assumes a separate solution for Front haul termination and focuses the entire PCle bandwidth on LDPC FEC, HARQ, Rate matching and CRC attach/detach functions.

ZU48DR RFSoC includes 4G/5G encode and decode acceleration along with wrapper functions such as rate matching and CRC logic. Zynq UltraScale+ RFSoC has hardened soft-decision forward error correction (SD-FEC) blocks, which can perform high-performance encode and decode with low cost, latency and power. The T2 card has a PCle® Gen3 x16/2x Gen4x8 connector and can plug into any commercial off the shelf (COTS) server thus improving network scalability, agility and total deployment costs.

The board is a single slot half height, half length (HHHL) form factor. The card is passively cooled and has a maximum electrical power limit of 50W. The high throughput, low latency and low power of T2 card make it an ideal solution for 5G massive MIMO radio configurations.



TARGET APPLICATIONS

- > 5G L1 baseband acceleration and LDPC decoding/encoding with SD-FEC integrated block in network base station applications
- > 4G L1 baseband acceleration with Turbo coding FEC mechanism

PERFORMANCE

Virtualization requires significant acceleration of latency-sensitive and compute-intensive functions. The T2 card performance metrics below are based on in-lab measurements of the card reference design.

Peak throughput and average latency of each SD-FEC core is given. The ZU48DR device has 8 SD-FEC cores which can be configured as LDPC encoder/decoder or turbo decoder to achieve the desired throughput.

L1 LDPC Performance	Throughput per SD-FEC Core	Average Latency
Encoder	35 Gb/s	<10usec
Decoder	12 Gb/s	< 10usec

SPECIFICATION

SoCs	Zynq UltraScale+ RFSoC ZU48DR		
SoC Resources	System Logic Cells - 930KCLB LUT - 425KSDFEC - 8	DSP Slices - 4,272Total BRAM - 38MbMax Distributed RAM - 13Mb	> URAM - 22.5mb



SPECIFICATION

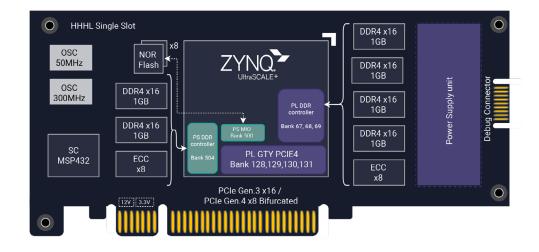
Form Factor	 Half Height Half Lenght (HHHL) PCB Thickness: 1.59mm Length: 167.65mm X16 PCle Form Factor Primary Side Width: 14.22mm Height: 56.14mm Secondary Side Width: 2.5mm 		
PCle Interface	PCIe [®] Gen3 x16/ 2x Gen4x8		
On Board Memory	 1x Banks of 4GB x72 (64 bit +8bit ECC) - PL 1x Banks of 2GB x40 (32 bit +8bit ECC) - PS Total Capacity 4GB in PL 		
	Total Capacity 2GB in PS		
In System Upgrade	Standard Xilinx tandem and partial reconfiguration support for the device		
Programming	1x 2Gb QSPI NOR Flash for FPGA configuration for ZU48DR		
External Interfaces	Xilinx DMB2 connector for JTAG support (FPGA programming and debug) and access to BMC QSPI for ARM boot code and FPGA images		
Reference Design	Vivado® design (diagnostic bit file) and commands for testing all datapath interfaces available for diagnostic bit files for both FPGAs		
Cooling	Passive cooling, custom heat sink		
Board Management Controller (BMC)	 Power Sequencing and Reset Field Upgrades FPGA Configuration and Control 		
Power	55W typical		

Xilinx RFSoC details here: www.xilinx.com/support/documentation/selection-guides/zynq-usp-rfsoc-product-selection-guide.pdf

HIGH LEVEL BLOCK DIAGRAM

L1 Offload

- > LDPC/TURBO codecs
- > Polar codecs
- > HARQ management
- > Codec Surrounding/Wrapper logic
 - CRC logic
 - Rate Matching/De-Matching



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Printed in the U.S.A. AC11-10-21